

Pch -20V -200mA Small Signal MOSFET

V_{DSS}	-20V
$R_{DS(on)}$ (Max.)	1.2Ω
I_D	±200mA
P_D	150mW

●Outline

SOT-723



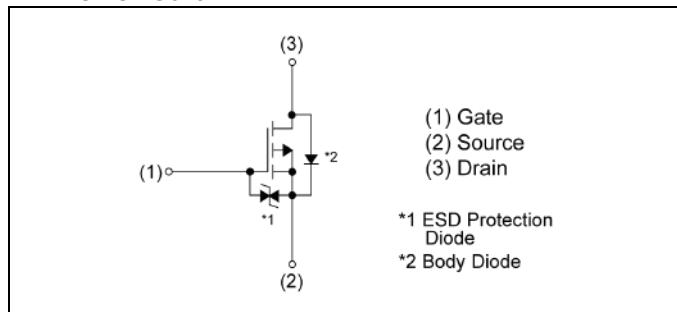
●Features

- 1) High speed switching
- 2) Small package (SOT-723).
- 3) Low voltage drive(1.2V) makes this device ideal for portable equipment.

●Application

Switching

●Inner circuit



●Absolute maximum ratings ($T_a = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	-20	V
Continuous drain current	I_D	±200	mA
Pulsed drain current	$I_{DP}^{\ast 1}$	±800	mA
Gate - Source voltage	V_{GSS}	±10	V
Power dissipation	$P_D^{\ast 2}$	150	mW
Junction temperature	T_j	150	°C
Operating junction and storage temperature range	T_{stg}	-55 to +150	°C

● Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - ambient	R_{thJA}^{*2}	-	-	833	°C/W

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = -1\text{mA}$	-20	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	$I_D = -1\text{mA}$ referenced to 25°C	-	-21.9	-	mV/°C
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}$	-	-	-1	μA
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 10\text{V}, V_{DS} = 0\text{V}$	-	-	± 10	μA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = -10\text{V}, I_D = -100\mu\text{A}$	-0.3	-	-1.0	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	$I_D = -1\text{mA}$ referenced to 25°C	-	2.4	-	mV/°C
Static drain - source on - state resistance	$R_{DS(on)}^{*3}$	$V_{GS} = -4.5\text{V}, I_D = -200\text{mA}$	-	0.8	1.2	Ω
		$V_{GS} = -2.5\text{V}, I_D = -100\text{mA}$	-	1.0	1.5	
		$V_{GS} = -1.8\text{V}, I_D = -100\text{mA}$	-	1.3	2.2	
		$V_{GS} = -1.5\text{V}, I_D = -40\text{mA}$	-	1.6	3.5	
		$V_{GS} = -1.2\text{V}, I_D = -10\text{mA}$	-	2.4	9.6	
Forward Transfer Admittance	$ Y_{fsl} ^{*3}$	$V_{DS} = -10\text{V}, I_D = -200\text{mA}$	200	-	-	mS

*1 $P_w \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*2 Each terminal mounted on a reference land.

*3 Pulsed

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input capacitance	C_{iss}	$V_{GS} = 0\text{V}$ $V_{DS} = -10\text{V}$ $f = 1\text{MHz}$	-	115	-	pF
Output capacitance	C_{oss}		-	10	-	
Reverse transfer capacitance	C_{rss}		-	6	-	
Turn - on delay time	$t_{d(on)}^{*3}$	$V_{DD} \approx -10\text{V}, V_{GS} = -4.5\text{V}$ $I_D = -100\text{mA}$ $R_L \approx 100\Omega$ $R_G = 10\Omega$	-	6	-	ns
Rise time	t_r^{*3}		-	4	-	
Turn - off delay time	$t_{d(off)}^{*3}$		-	17	-	
Fall time	t_f^{*3}		-	17	-	

● Gate charge characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q_g^{*3}	$V_{DD} \approx -10\text{V},$ $I_D = -200\text{mA},$ $V_{GS} = -4.5\text{V}$	-	1.4	-	nC
Gate - Source charge	Q_{gs}^{*3}		-	0.3	-	
Gate - Drain charge	Q_{gd}^{*3}		-	0.3	-	

● Body diode electrical characteristics (Source-Drain) ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Continuous forward current	I_S	$T_a = 25^\circ\text{C}$	-	-	-100	mA
Pulse forward current	I_{SP}^{*1}		-	-	-800	
Forward voltage	V_{SD}^{*3}	$V_{GS} = 0\text{V}, I_S = -200\text{mA}$	-	-	-1.2	V

●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

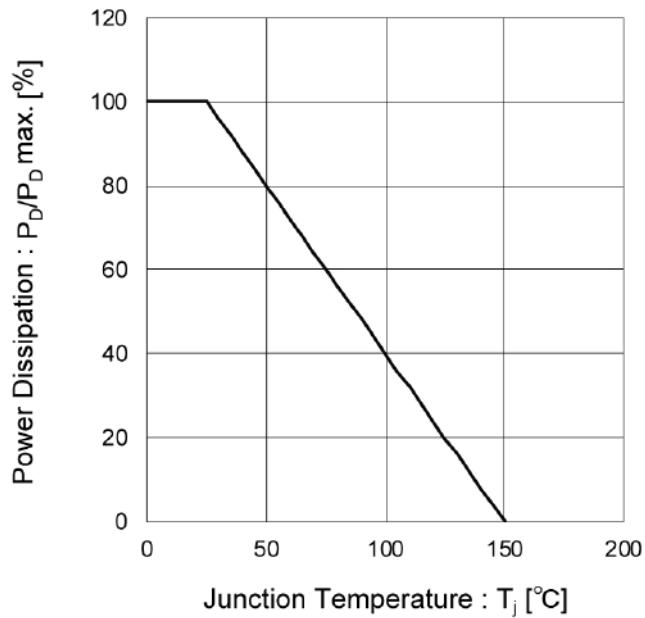


Fig.2 Drain Current Derating Curve

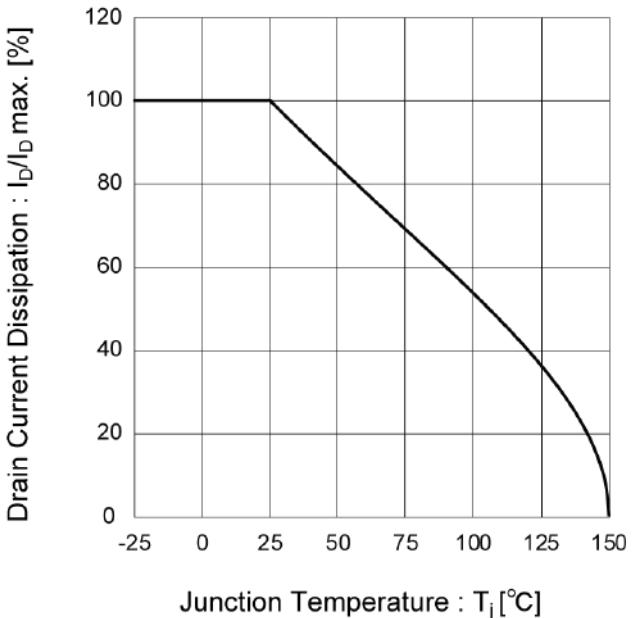


Fig.3 Typical Output Characteristics(I)

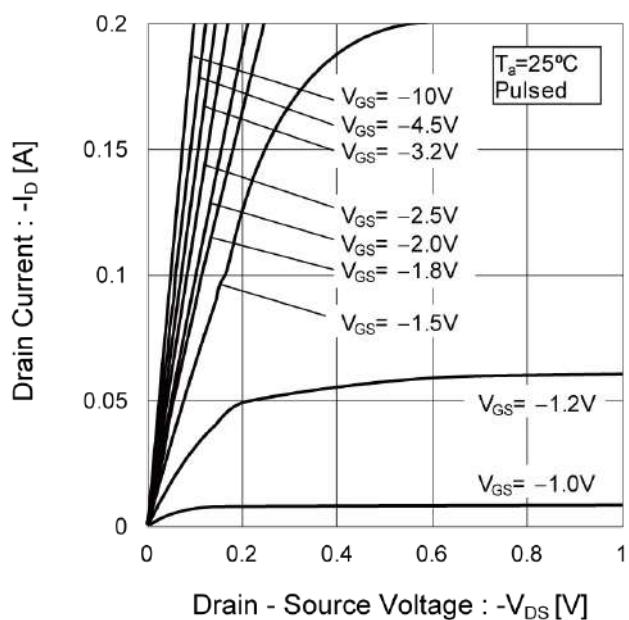
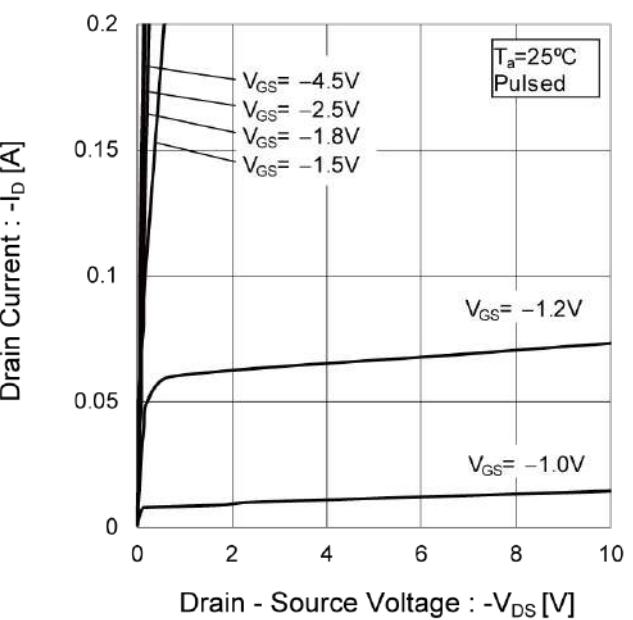


Fig.4 Typical Output Characteristics(II)



● Electrical characteristic curves

Fig.5 Breakdown Voltage vs.
Junction Temperature

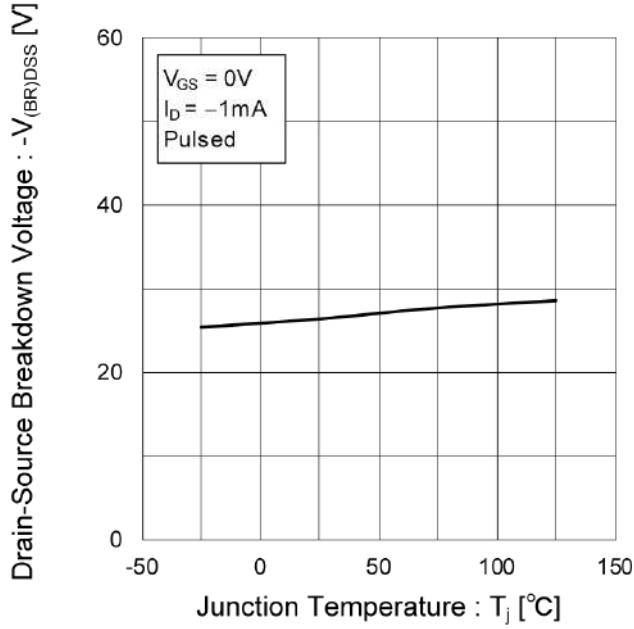


Fig.6 Typical Transfer Characteristics

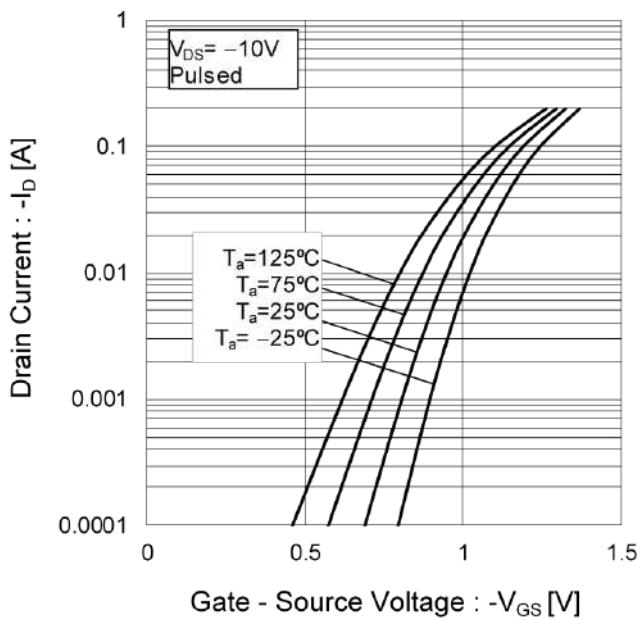


Fig.7 Gate Threshold Voltage vs.
Junction Temperature

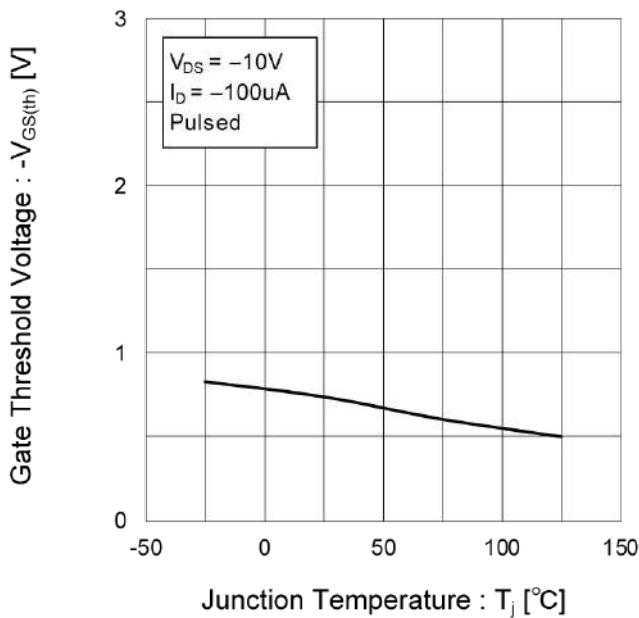
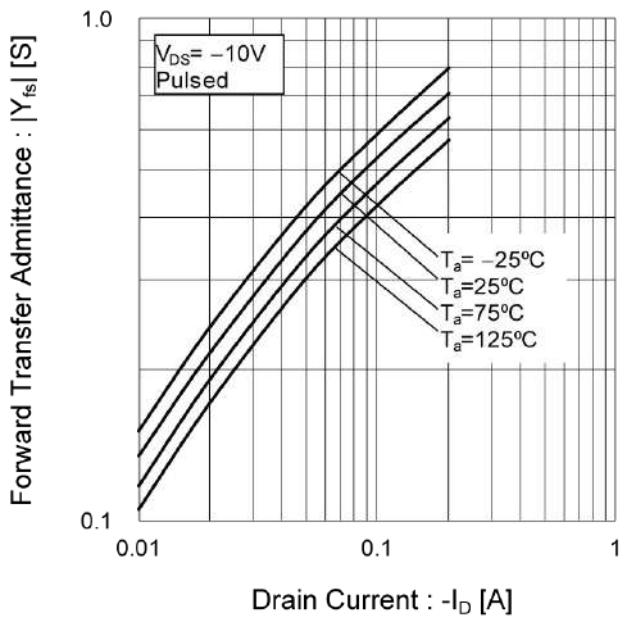


Fig.8 Forward Transfer Admittance vs.
Drain Current



● Electrical characteristic curves

Fig.9 Static Drain - Source On - State
Resistance vs. Gate Source Voltage

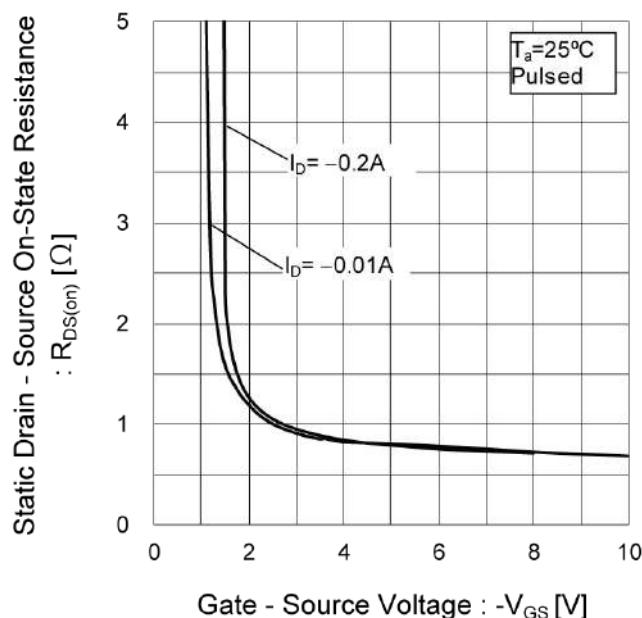


Fig.10 Static Drain - Source On - State
Resistance vs. Junction Temperature

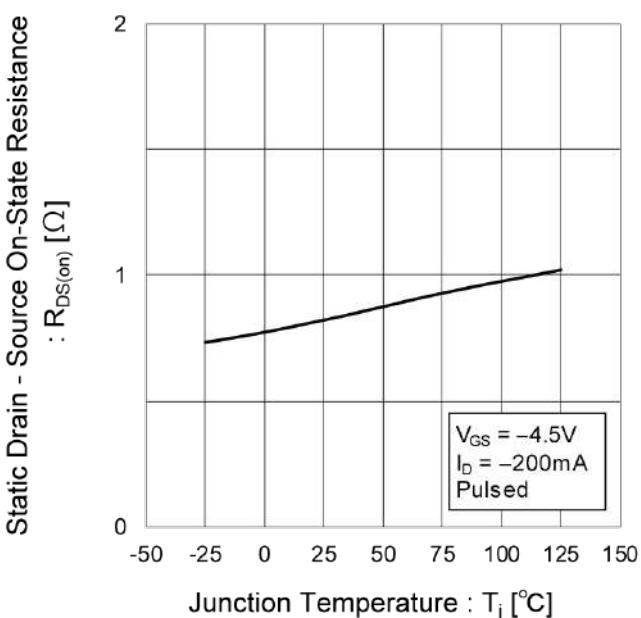


Fig.11 Static Drain - Source On - State
Resistance vs. Drain Current (I)

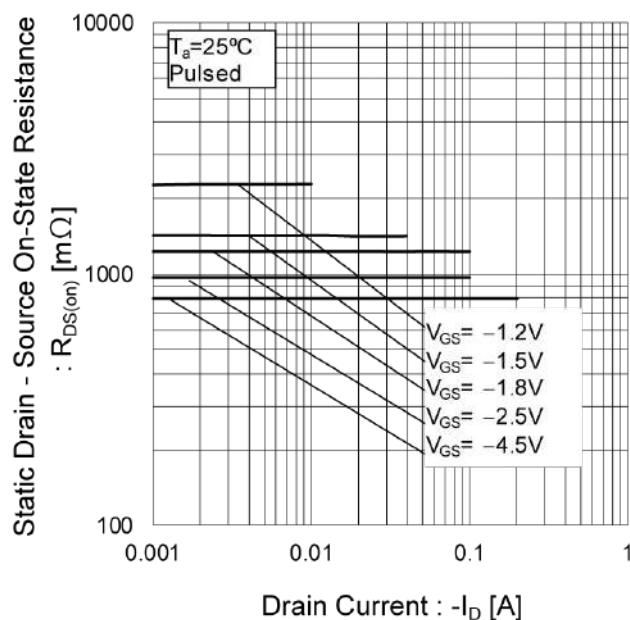
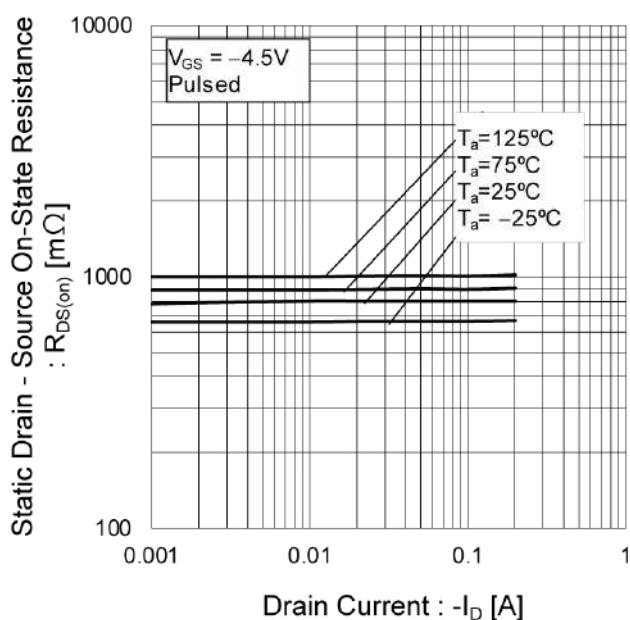


Fig.12 Static Drain - Source On - State
Resistance vs. Drain Current (II)



● Electrical characteristic curves

Fig.13 Static Drain - Source On - State
Resistance vs. Drain Current (III)

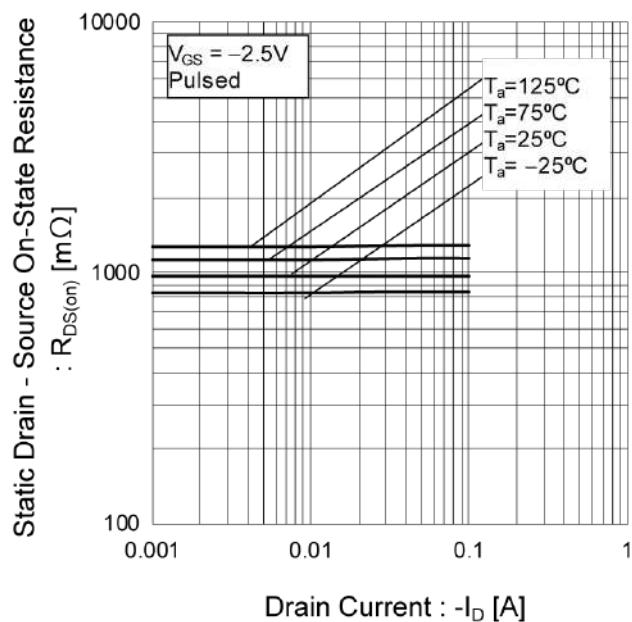


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (IV)

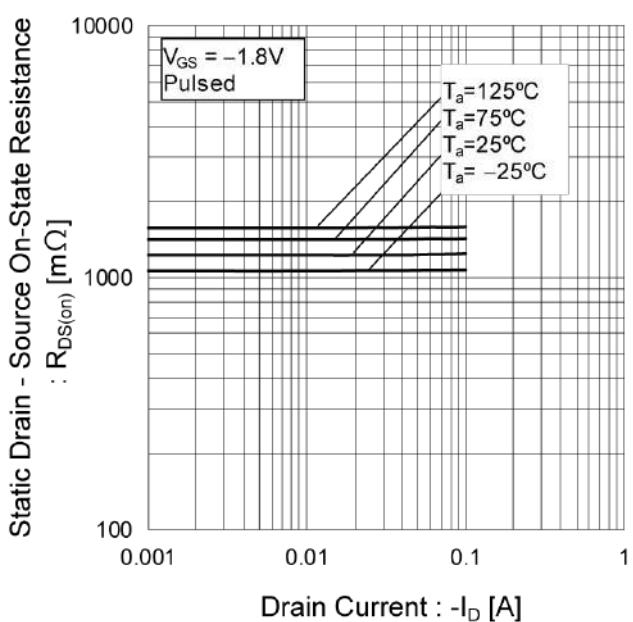


Fig.15 Static Drain - Source On - State
Resistance vs. Drain Current (V)

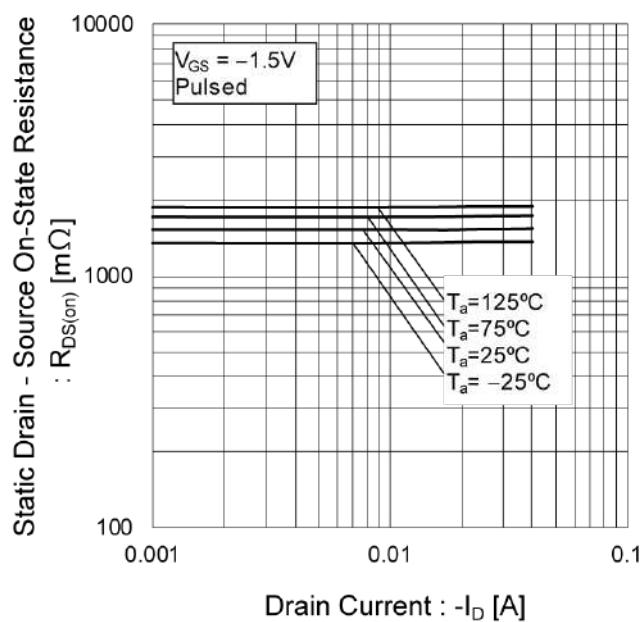
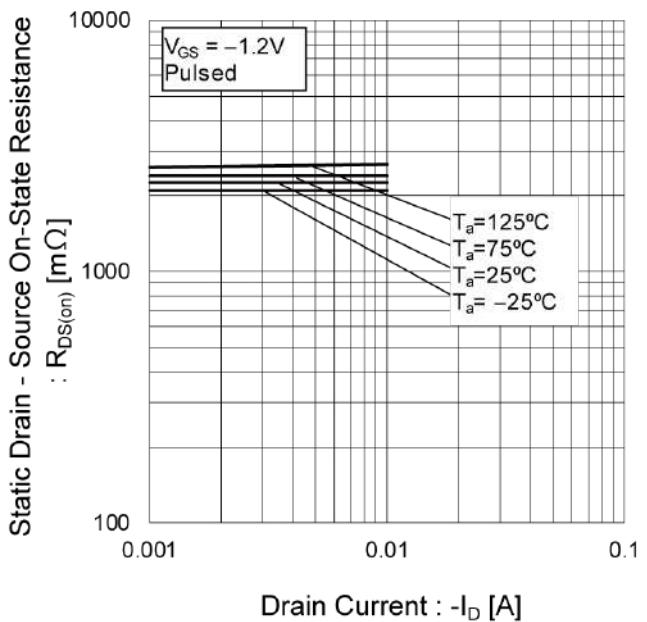


Fig.16 Static Drain - Source On - State
Resistance vs. Drain Current (VI)



● Electrical characteristic curves

Fig.17 Typical Capacitance vs.
Drain - Source Voltage

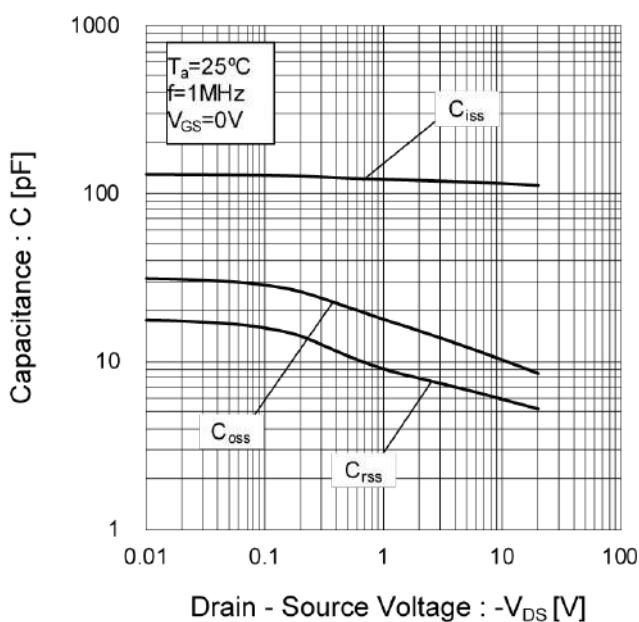


Fig.18 Switching Characteristics

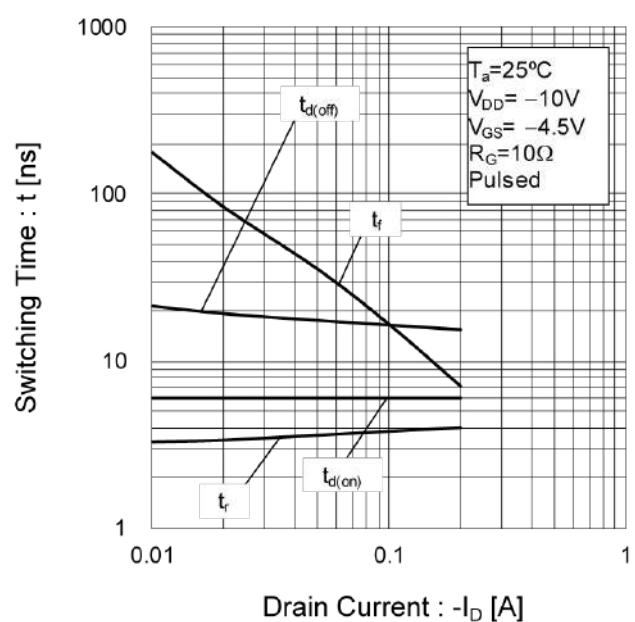
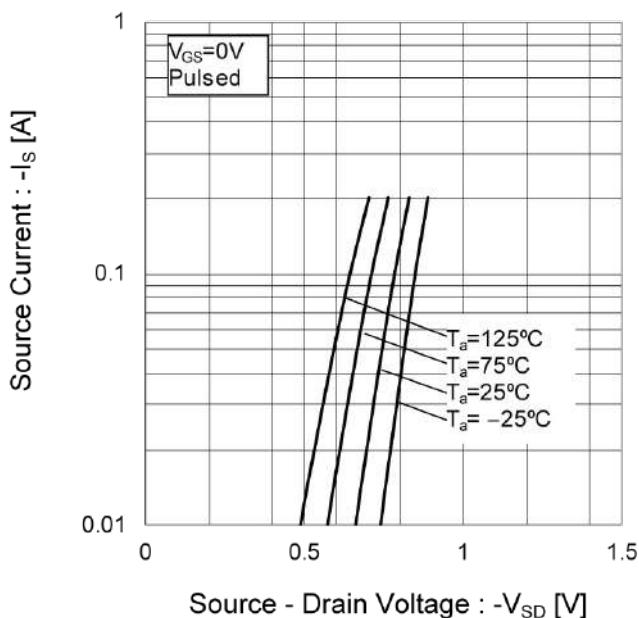


Fig.19 Source Current vs.
Source Drain Voltage



● Measurement circuits

Fig. 1-1 SWITCHING TIME MEASUREMENT CIRCUIT

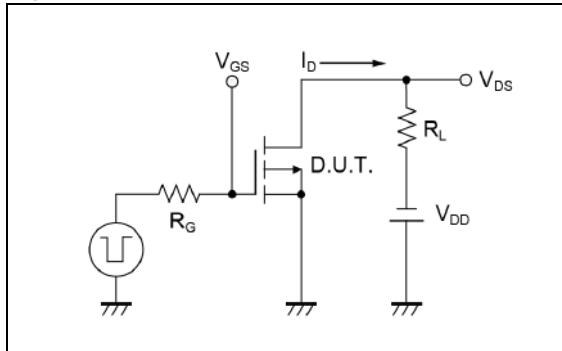


Fig. 2-1 GATE CHARGE MEASUREMENT CIRCUIT

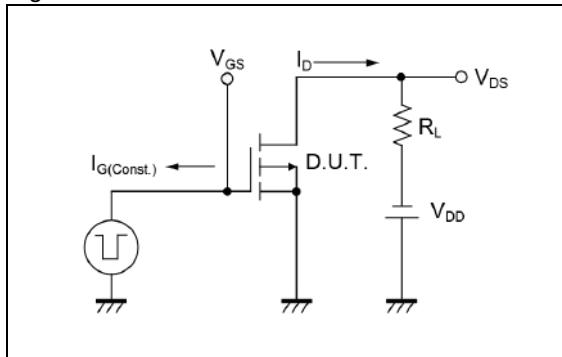


Fig. 1-2 SWITCHING WAVEFORMS

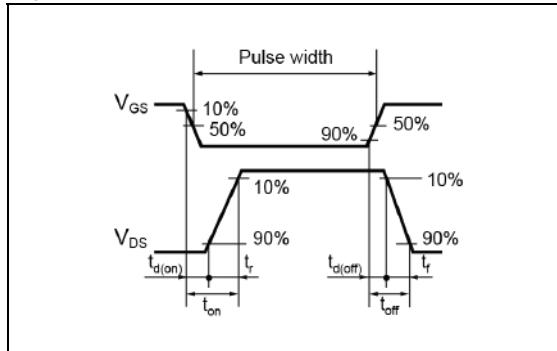
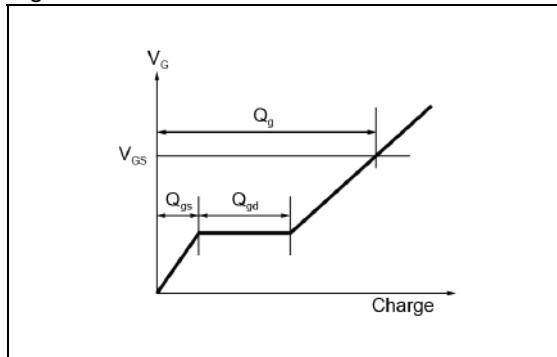
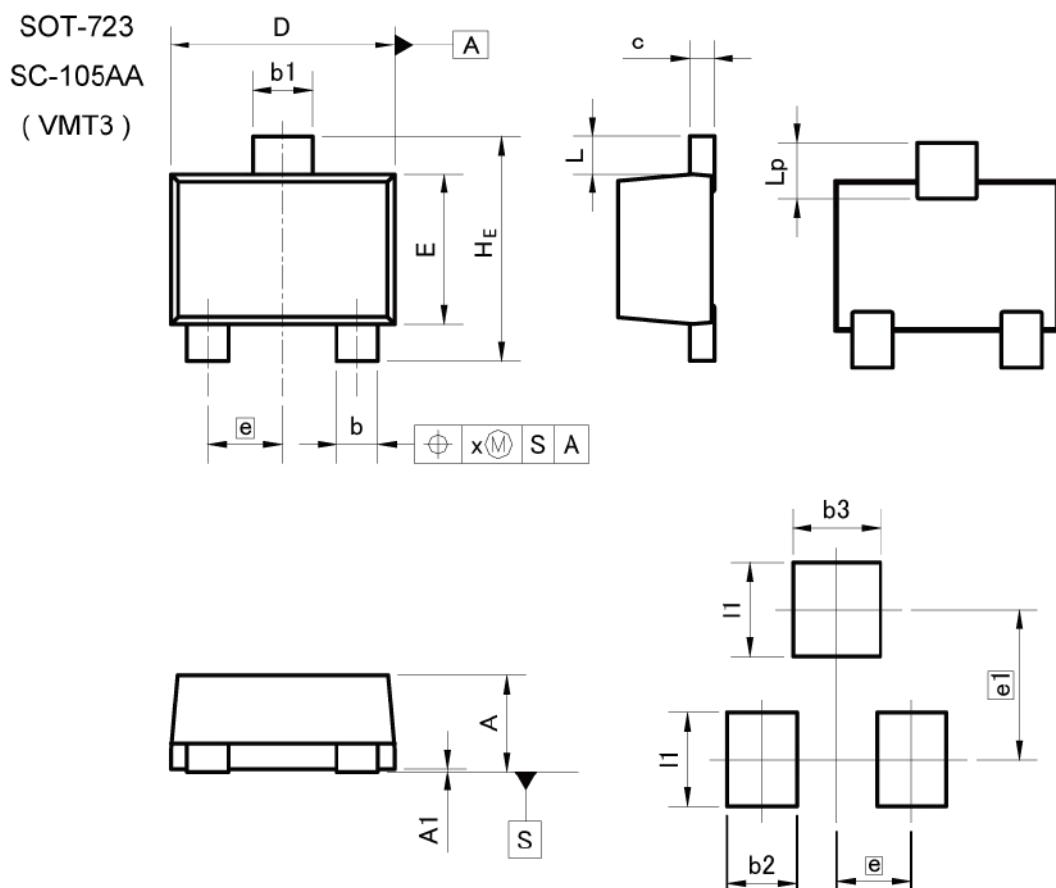


Fig. 2-2 GATE CHARGE WAVEFORM



●Dimensions



Pattern of terminal position areas
[Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
c	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
e	0.40		0.02	
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
x	—	0.10	—	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	—	0.37	—	0.015
b3	—	0.47	—	0.019
e1	0.80		0.031	
II	—	0.50	—	0.020

Dimension in mm/inches